

MPC5554 Microcontroller Product Brief

The MPC5554 is the first member of a family of next generation microcontrollers based on the PowerPC™ Book E architecture that enhances the PowerPC architecture's fit in embedded applications. It is 100% user mode compatible (with floating point library) with the classic PowerPC instruction set. This document provides an overview of the MPC5554 microcontroller features, including the major functional components.

The MPC5554 device's on-chip modules include the following:

- Single issue, 32-bit PowerPC Book E-compliant e200z6 CPU core complex
- 64-channel enhanced direct memory access controller (eDMA)
- Interrupt controller (INTC) capable of handling 286 selectable-priority interrupt sources
- Frequency modulated phase-locked loop (FMPLL)
- External bus interface (EBI) with error correction status module (ECSM)
- System integration unit (SIU)

Table of Contents

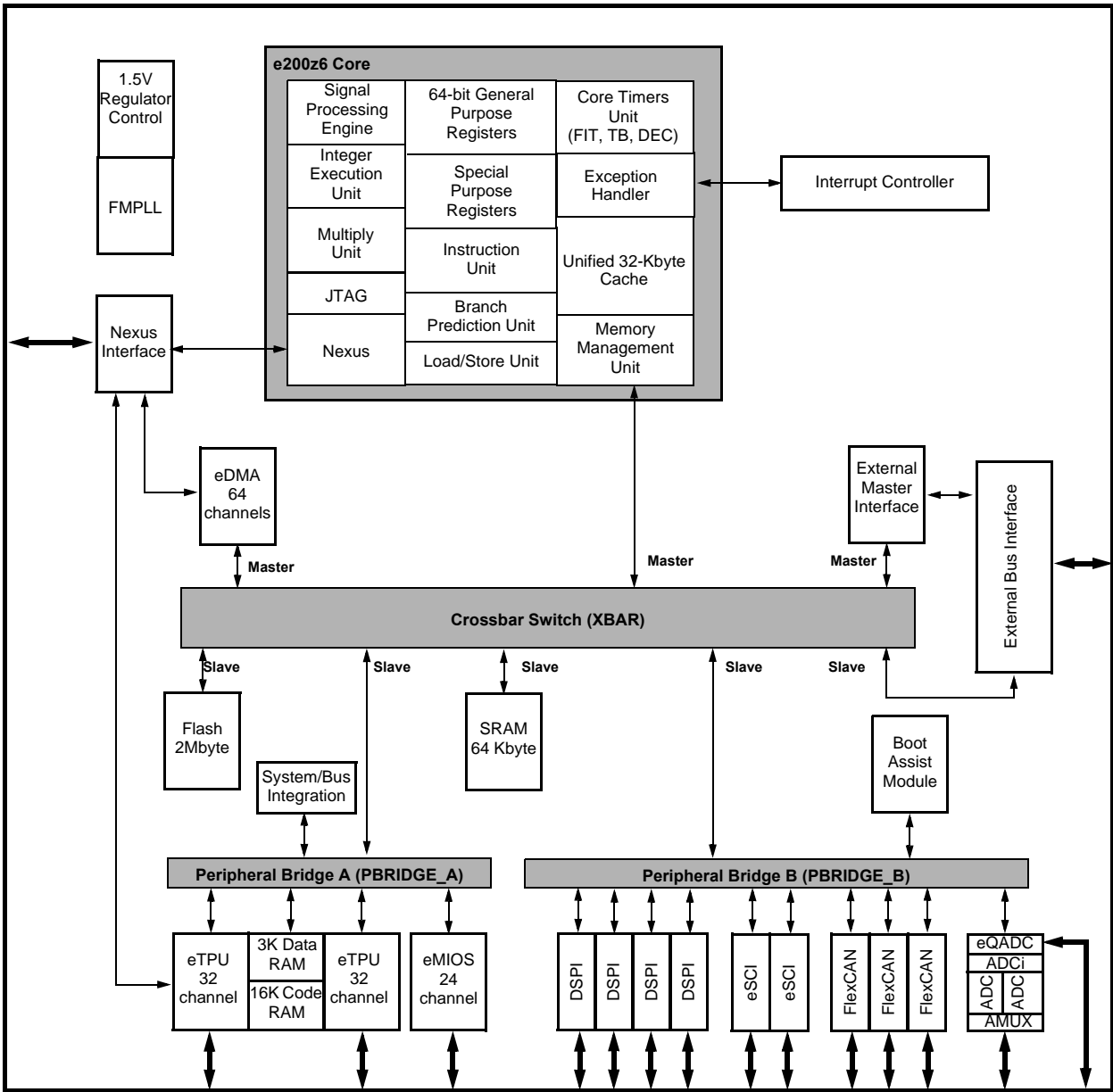
1	Block Diagram	3
2	Features	4

- 2 Mbytes on-chip Flash with Flash bus interface unit (FBIU)
- 64 Kbytes on-chip static RAM
- Boot assist module (BAM)
- 24-channel enhanced modular I/O system (eMIOS)
- 2 enhanced time processor unit (eTPU) engines. Each eTPU engine controls 32 hardware channels.
- Enhanced queued analog-to-digital converter (eQADC)
- 4 deserial serial peripheral interface (DSPI) modules
- 2 enhanced serial communication interface (eSCI) modules
- 3 controller area network (FlexCAN) modules
- Nexus development interface (NDI) per IEEE-ISTO 5001-2003 standard
- Device/board test support per Joint Test Action Group (JTAG) of IEEE (IEEE 1149.1)

To locate any published errata or updates for this document, refer to the web site at <http://www.freescale.com>.

1 Block Diagram

Figure 1 shows a top-level block diagram of the MPC5554.



LEGEND

MPC5500 Device Module Acronyms

- CAN** – Controller area network (FlexCAN)
- DSPI** – Deserial/serial peripheral interface
- DMA** – Enhanced direct memory access
- eMIOS** – Enhanced modular I/O system
- eQADC** – Enhanced queued analog/digital converter
- eSCI** – Enhanced serial communications interface
- eTTPU** – Enhanced time processing units
- FMPLL** – Frequency modulated phase-locked loop
- SRAM** – Static RAM

e200z6 Core Component Acronyms

- DEC** – Decrementer
- FIT** – Fixed interval timer
- TB** – Time base
- WDT** – Watchdog timer

Figure 1. MPC5554 Block Diagram

2 Features

This section provides a high-level description of the major features of the MPC5554.

- High performance e200z6 core processor
 - 32-bit PowerPC Book E compliant CPU
 - 32 64-bit general-purpose registers (GPRs)
 - Memory management unit (MMU) with 32-entry, fully-associative translation look-aside buffer (TLB)
 - Branch processing unit
 - Fully pipelined load/store unit
 - 32-Kbyte unified cache with line locking
 - 8-way set associative
 - 2 32-bit fetches per clock
 - 8-entry store buffer
 - Way locking
 - Supports assigning cache as instruction or data only on a per way basis
 - Supports tag and data parity
 - Vectored interrupt support
 - Interrupt latency < 70 ns @132MHz (measured from interrupt request to execution of first instruction of interrupt exception handler)
 - Reservation instructions for implementing read-modify-write constructs (internal SRAM and Flash)
 - Signal processing engine (SPE) auxiliary processing unit (APU) operating on 64-bit GPRs
 - Floating point
 - IEEE® 754 compatible with software wrapper
 - Single precision in hardware and double precision with software library
 - Conversion instructions between single precision floating point and fixed point
 - Long cycle time instructions, except for guarded loads, do not increase interrupt latency in the MPC5554. To reduce latency, long cycle time instructions are aborted upon interrupt requests.
 - Extensive system development support through Nexus debug module
- Crossbar switch (XBAR)
 - 3 master ports; 5 slave ports
 - 32-bit address bus; 64-bit data bus
 - Simultaneous accesses from different masters to different slaves (there is no clock penalty when a parked master accesses a slave)

- Enhanced direct memory access (eDMA) controller
 - 64 channels support independent 8-, 16-, 32-, or 64-bit single value or block transfers
 - Supports variable sized queues and circular queues
 - Source and destination address registers are independently configured to post-increment or remain constant
 - Each transfer is initiated by a peripheral, CPU, or eDMA channel request
 - Each eDMA channel can optionally send an interrupt request to the CPU on completion of a single value or block transfer
- Interrupt controller (INTC)
 - 308 total interrupt vectors
 - 278 peripheral interrupt requests
 - plus 8 software settable sources
 - plus 22 reserved interrupts
 - Unique 9-bit vector per interrupt source
 - 16 priority levels with fixed hardware arbitration within priority levels for each interrupt source
 - Priority elevation for shared resources
- Frequency modulated phase-locked loop (FMPLL)
 - Input clock frequency from 8 MHz to 20 MHz
 - Current controlled oscillator (ICO) range from 50 MHz to maximum device frequency
 - Reduced frequency divider (RFD) for reduced frequency operation without re-lock
 - 4 selectable modes of operation
 - Programmable frequency modulation
 - Lock detect circuitry continuously monitors lock status
 - Loss of clock (LOC) detection for reference and feedback clocks
 - Self-clocked mode (SCM) operation
 - On-chip loop filter (reduces number of external components required)
 - Engineering clock output
- External bus interface (EBI)
 - 1.8V–3.3V I/O nominal I/O voltage
 - Memory controller with support for various memory types
 - 32-bit data bus and 24-bit address bus with transfer size indication
 - Selectable drive strength
 - Configurable bus speed modes
 - Support for external master accesses to internal addresses
 - Burst support

Features

- Bus monitor
- Chip selects: 4 chip select ($\overline{CS}[0:3]$) signals
- Configurable wait states
- System integration unit (SIU)
 - Centralized GPIO control of 214 I/O and bus pins
 - Centralized pad control on a per-pin basis
 - System reset monitoring and generation
 - External interrupt inputs, filtering, and control
- Error correction status module (ECSM)
 - Configurable error-correcting codes (ECC) reporting for internal SRAM and Flash memories
- On-chip Flash
 - 2 Mbytes burst Flash memory
 - 256K × 64 bit configuration
 - Censorship protection scheme to prevent Flash content visibility
 - Hardware read-while-write feature that allows blocks to be erased/programmed while other blocks are being read (used for EEPROM emulation and data calibration)
 - 20 blocks, ranging from 16 Kbytes to 128 Kbytes, to support features such as boot block, operating system block, and EEPROM emulation
 - Read while write with multiple partitions
 - Parallel programming mode to support rapid end of line programming
 - Hardware programming state machine
- Configurable cache memory, 32-Kbyte
 - 8-way set-associative, unified (instruction and data) cache
- On-chip, internal static RAM (SRAM)
 - 64-Kbyte general-purpose RAM; 32 Kbytes on standby power
 - ECC performs single bit correction, double bit error detection
- Boot assist module (BAM)
 - Enables and manages the transition of MCU from reset to user code execution in the following configurations:
 - User application can boot from internal or external Flash memory
 - Download and execution of code via FlexCAN or eSCI
- Enhanced modular I/O system (eMIOS)
 - 24 orthogonal channels with double action, PWM, and modulus counter functionality
 - Supports all DASM and PWM modes of MIOS14 (MPC5xx)
 - 4 selectable time bases plus shared time or angle counter bus
 - DMA and interrupt request support

- Motor control capability
- Enhanced time processor unit (eTPU)
 - MPC5554 has 2 eTPU engines
 - Each eTPU engine is an event-triggered timer subsystem
 - High level assembler/compiler
 - 32 channels per engine
 - 24-bit timer resolution
 - 16-Kbyte shared code memory
 - 3-Kbyte shared data memory
 - Variable number of parameters allocatable per channel
 - Double match/capture channels
 - Angle clock hardware support
 - Shared time or angle counter bus for all eTPU and eMIOS modules
 - DMA and interrupt request support
 - Nexus Class 3 Debug support (with some Class 4 support)
- Enhanced queued analog/digital converter (eQADC)
 - 2 independent ADCs with 12-bit A/D resolution
 - Common mode conversion range of 0–5V
 - 40 single-ended inputs channels, expandable to 65 channels with external multiplexers
 - 4 pairs of differential analog input channels.
 - 10-bit accuracy at 400 ksamples/s, 8-bit accuracy at 800 ksamples/s
 - Supports 6 FIFO queues with fixed priority.
 - Queue modes with priority-based preemption; initiated by software command, internal (eTPU and eMIOS), or external triggers
 - DMA and interrupt request support
 - Supports all functional modes from QADC (MPC5xx family)
- 4 Deserial serial peripheral interface modules (DSPI)
 - Serial peripheral interface (SPI)
 - Full duplex communication ports with interrupt and eDMA request support
 - Supports all functional modes from QSPI submodule of QSMCM (MPC5xx family)
 - Support for queues in RAM
 - 6 chip selects, expandable to 64 with external demultiplexers
 - Programmable frame size, baud rate, clock delay, and clock phase on a per frame basis
 - Modified SPI mode for interfacing to peripherals with longer setup time requirements
 - Deserial serial interface (DSI)
 - Pin reduction by hardware serialization and deserialization of eTPU and eMIOS channels

Features

- Chaining of DSI submodules
 - Triggered transfer control and change in data transfer control (for reduced EMI)
- 2 enhanced serial communication interface (eSCI) modules
 - UART mode provides NRZ format and half or full duplex interface
 - eSCI bit rate up to 1 Mbps
 - Advanced error detection, and optional parity generation and detection
 - Word length programmable as 8 or 9 bits
 - Separately enabled transmitter and receiver
 - LIN Support
 - DMA support
 - Interrupt request support
- 3 FlexCANs
 - 64 message buffers each
 - Full implementation of the CAN protocol specification, Version 2.0B
 - Based on and including all existing features of the Freescale TouCAN module
 - Programmable acceptance filters
 - Short latency time for high priority transmit messages
 - Arbitration scheme according to message ID or message buffer number
 - Listen only mode capabilities
 - Programmable clock source: system clock or oscillator clock
- Nexus development interface (NDI)
 - Per IEEE®-ISTO 5001-2003
 - Real time development support for e200z6 core and eTPU engines through Nexus Class 3 (some Class 4 support)
 - Data trace of eDMA accesses
 - Read and write access
 - Configured via the IEEE® 1149.1 (JTAG) port
 - High bandwidth mode for fast message transmission
 - Reduced bandwidth mode for reduced pin usage
- IEEE® 1149.1 JTAG controller (JTAGC)
 - IEEE® 1149.1-2001 Test Access Port (TAP) interface
 - A JCOMP input that provides the ability to share the TAP. Selectable modes of operation include JTAGC/debug or normal system operation.
 - A 5-bit instruction register that supports IEEE® 1149.1-2001 defined instructions
 - A 5-bit instruction register that supports additional public instructions
 - 3 test data registers: bypass, boundary scan, and device identification

- A TAP controller state machine that controls the operation of the data registers, instruction register and associated circuitry
- Voltage regulator controller
 - Provides a low cost solution to power the core logic. It reduces the number of power supplies required from the customer power supply chip.
- POR block
 - Provides initial reset condition up to the voltage at which pins ($\overline{\text{RESET}}$) can be read safely. It does not guarantee the safe operation of the chip at specified minimum operating voltages.

How to Reach Us:

Home Page:

www.freescale.com

E-mail:

support@freescale.com

USA/Europe or Locations Not Listed:

Freescale Semiconductor
Technical Information Center, CH370
1300 N. Alma School Road
Chandler, Arizona 85224
+1-800-521-6274 or +1-480-768-2130
support@freescale.com

Europe, Middle East, and Africa:

Freescale Halbleiter Deutschland GmbH
Technical Information Center
Schatzbogen 7
81829 Muenchen, Germany
+44 1296 380 456 (English)
+46 8 52200080 (English)
+49 89 92103 559 (German)
+33 1 69 35 48 48 (French)
support@freescale.com

Japan:

Freescale Semiconductor Japan Ltd.
Headquarters
ARCO Tower 15F
1-8-1, Shimo-Meguro, Meguro-ku,
Tokyo 153-0064, Japan
0120 191014 or +81 3 5437 9125
support.japan@freescale.com

Asia/Pacific:

Freescale Semiconductor Hong Kong Ltd.
Technical Information Center
2 Dai King Street
Tai Po Industrial Estate
Tai Po, N.T., Hong Kong
+800 2666 8080
support.asia@freescale.com

For Literature Requests Only:

Freescale Semiconductor Literature Distribution Center
P.O. Box 5405
Denver, Colorado 80217
1-800-441-2447 or 303-675-2140
Fax: 303-675-2150
LDCForFreescaleSemiconductor@hibbertgroup.com

Information in this document is provided solely to enable system and software implementers to use Freescale Semiconductor products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits or integrated circuits based on the information in this document.

Freescale Semiconductor reserves the right to make changes without further notice to any products herein. Freescale Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Freescale Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters that may be provided in Freescale Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals", must be validated for each customer application by customer's technical experts. Freescale Semiconductor does not convey any license under its patent rights nor the rights of others. Freescale Semiconductor products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Freescale Semiconductor product could create a situation where personal injury or death may occur. Should Buyer purchase or use Freescale Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold Freescale Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Freescale Semiconductor was negligent regarding the design or manufacture of the part.



Freescale™ and the Freescale logo are trademarks of Freescale Semiconductor, Inc. All other product or service names are the property of their respective owners. The described product contains a PowerPC processor core. The PowerPC name is a trademark of IBM Corp. and used under license.

© Freescale Semiconductor, Inc. 2005. All rights reserved.

MPC5554PB
Rev. 2.2
02/2006